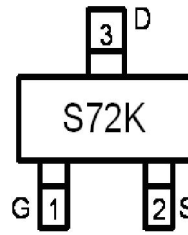


## Main Product Characteristics

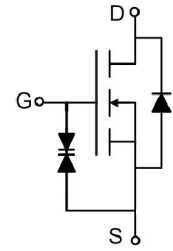
$V_{DSS}$	60V
$R_{DS(on)}$	2Ω(max.)
$I_D$	0.3A



SOT-23



Marking and Pin Assignment



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Special designed for PWM, load switching and general purpose applications
- Ultra low on-resistance with low gate charge
- Fast switching and reverse body recovery
- ESD Rating: 1000V HBM
- 150°C operating temperature
- Lead free product



## Description

It utilizes the latest processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications.

## Absolute Max Rating

Symbol	Parameter	Max.	Units
$I_D @ TC = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ ①	0.3	A
$I_{DM}$	Pulsed Drain Current②	1.2	
$P_D @ TC = 25^\circ C$	Power Dissipation③	0.63	W
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-to-Source Voltage	± 20	V
$T_J T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +150	°C

## Thermal Resistance

Symbol	Characteristics	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-ambient (t ≤ 10s) ④	—	200	°C/W

### Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

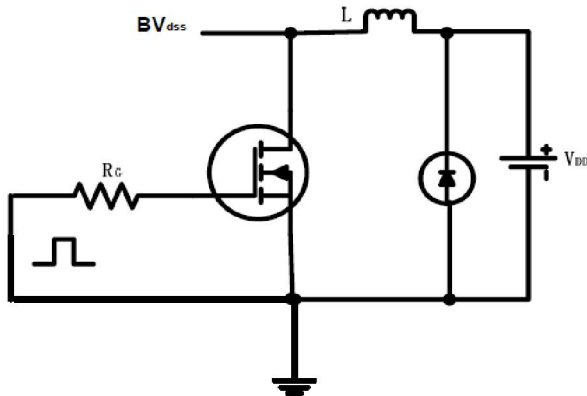
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	60	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$R_{DS(on)}$	Static Drain-to-Source on-resistance	—	1.5	2	$\Omega$	$V_{GS}=10V, I_D=0.5A$
		—	—	3		$V_{GS}=5V, I_D=0.05A$
$V_{GS(th)}$	Gate threshold voltage	1	—	2.5	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
$I_{DSS}$	Drain-to-Source leakage current	—	—	1	$\mu A$	$V_{DS} = 60V, V_{GS} = 0V$
$I_{GSS}$	Gate-to-Source forward leakage	—	—	$\pm 100$	nA	$V_{GS}=\pm 5V, V_{DS}=0V$
		—	—	$\pm 10$	$\mu A$	$V_{GS}=\pm 20V, V_{DS}=0V$
$t_{d(on)}$	Turn-on delay time	—	—	25	ns	$V_{GS}=10V, V_{DS}=30V,$ $I_D=0.2A, R_{GEN}=10\Omega$
$t_{d(off)}$	Turn-Off delay time	—	—	35		
$C_{iss}$	Input capacitance	—	40	—	pF	$V_{GS} = 0V$
$C_{oss}$	Output capacitance	—	16.6	—		$V_{DS} = 25V$
$C_{rss}$	Reverse transfer capacitance	—	9.5	—		$f = 1MHz$

### Source-Drain Ratings and Characteristics

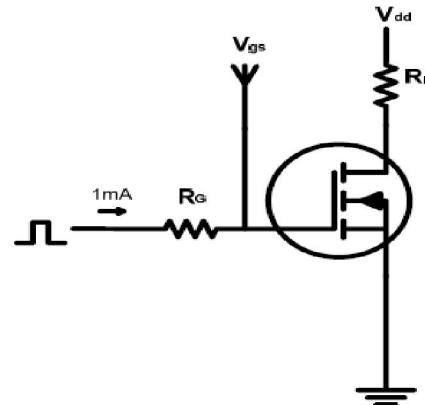
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$I_S$	Continuous Source Current (Body Diode)	—	—	0.3	A	MOSFET symbol showing the integral reverse p-n junction diode.
$I_{SM}$	Pulsed Source Current (Body Diode)	—	—	1.2	A	
$V_{SD}$	Diode Forward Voltage	—	—	1.3	V	

## Test circuits and Waveforms

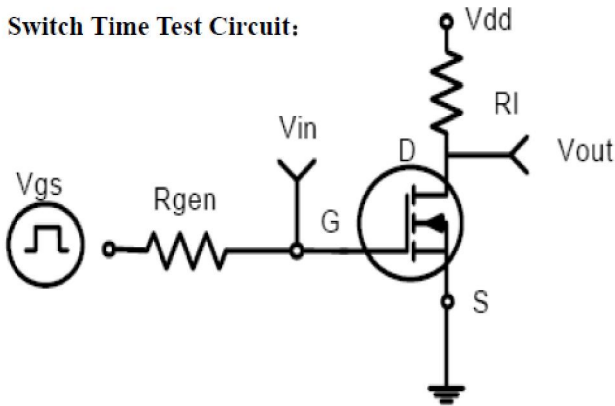
EAS test circuits:



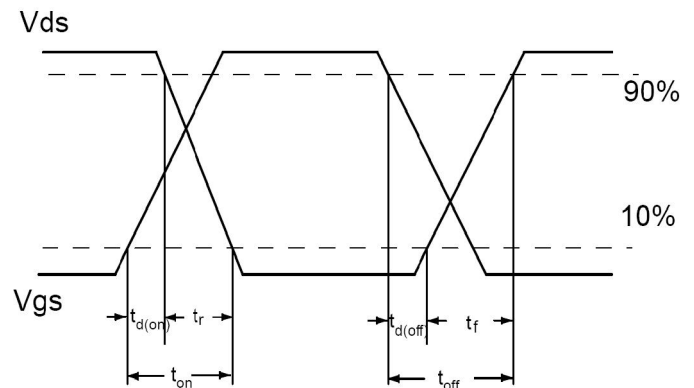
Gate charge test circuit:



Switch Time Test Circuit:



Waveforms:



## Notes:

- ① The maximum current rating is limited by bond-wires.
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ The power dissipation PD is based on max. junction temperature, using junction-to-case thermal resistance.
- ④ The value of  $R_{\theta JA}$  is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$
- ⑤ These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of  $T_{J(MAX)} = 150^\circ\text{C}$ .

## Typical Electrical and Thermal Characteristics

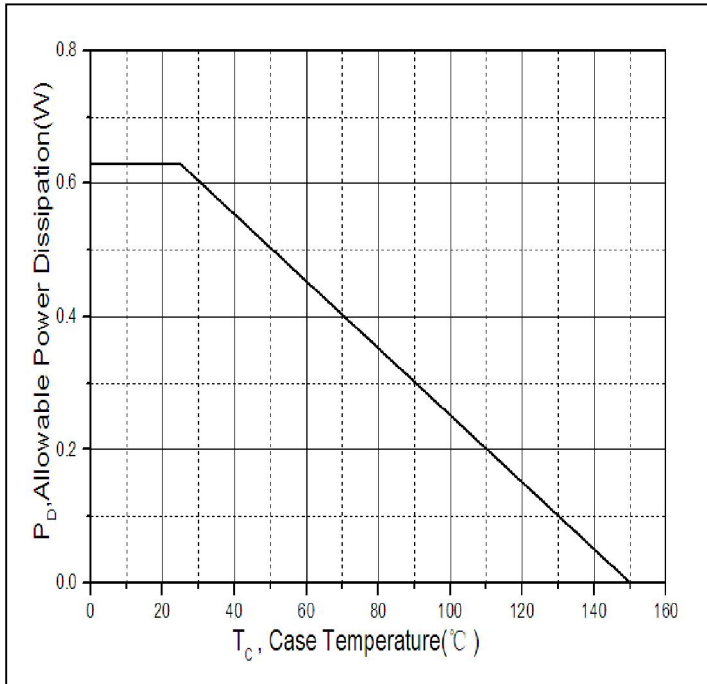


Figure 1. Power Dissipation Vs. Case Temperature

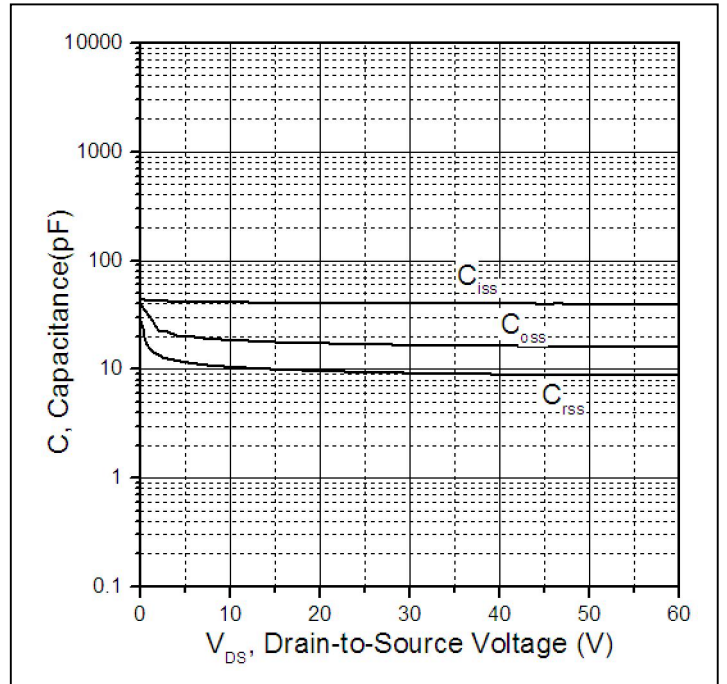


Figure 2. Typical Capacitance Vs. Drain-to-Source Voltage

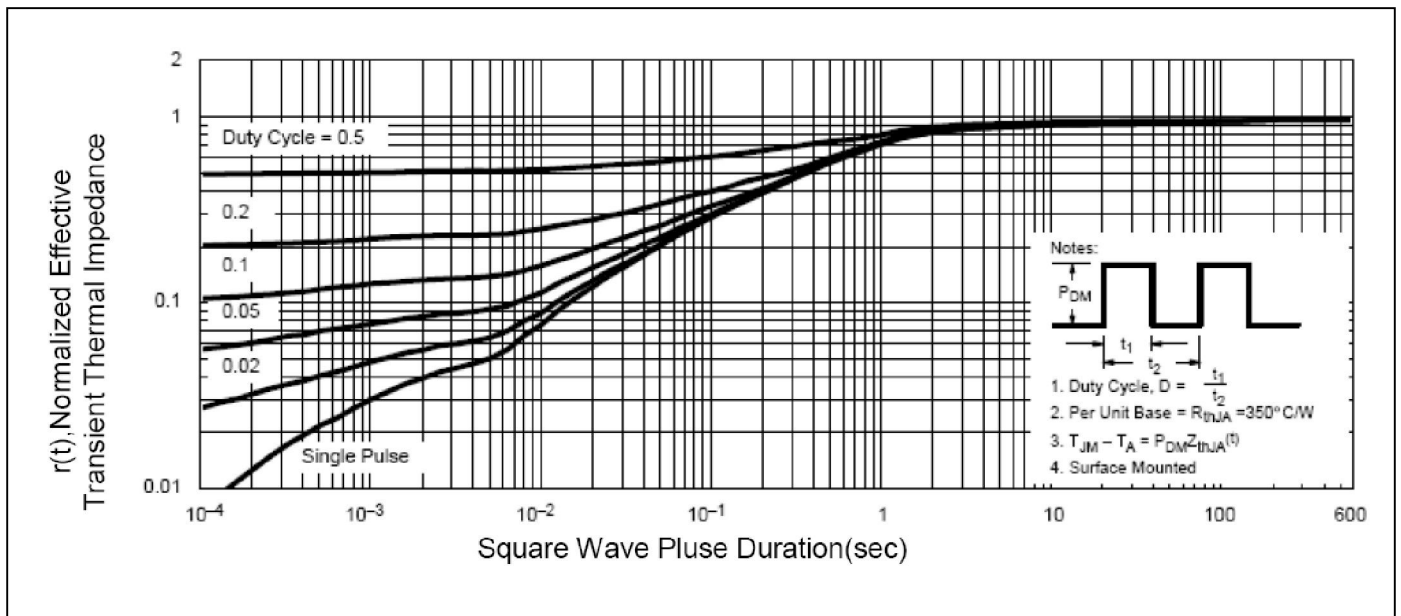


Figure3. Maximum Effective Transient Thermal Impedance, Junction-to-Case





### Ordering and Marking Information

**Device Marking: S72K**

Package (Available)  
SOT-23  
Operating Temperature Range  
C : -55 to 150 °C

### Devices per Unit

Package Type	Units/Tape	Tapes/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/ Carton Box
SOT-23	3000	10	30000	4	120000

### Reliability Test Program

Test Item	Conditions	Duration	Sample Size
High Temperature Reverse Bias(HTRB)	$T_j=125^{\circ}\text{C}$ to $150^{\circ}\text{C}$ @ 80% of Max $V_{DSS}/V_{CES}/V_R$	168 hours 500 hours 1000 hours	3 lots x 77 devices
High Temperature Gate Bias(HTGB)	$T_j=150^{\circ}\text{C}$ @ 100% of Max $V_{GSS}$	168 hours 500 hours 1000 hours	3 lots x 77 devices